

**PATENT**

**UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

Salman Akram

**Serial No.:** 10/791,191

**Filed:** March 2, 2004

**For:** METHOD OF IMPROVING COPPER  
INTERCONNECTS OF  
SEMICONDUCTOR DEVICES FOR  
BONDING

**Confirmation No.:** 1968

**Examiner:** L. Gurley

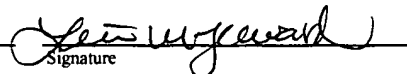
**Group Art Unit:** 2812

**Attorney Docket No.:** 2269-3854.3US  
(98-0854.03/US)

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

July 5, 2006  
Date

  
Signature

Leta M. Howard  
Name (Type/Print)

**AMENDMENT**

Mail Stop AMENDMENT  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

**Amendments to the Specification** begin on page 3 of this paper.

**Amendments to the Abstract** appear on page 22 of this paper.

**Serial No. 10/791,191**

**Amendments to the Claims** are reflected in the listing of claims which begins on page 23 of this paper.

**Amendments to the Drawings** appear on page 26 of this paper and include both attached replacement sheets and annotated sheets showing changes.

**Remarks** begin on page 27 of this paper.